

PCN Number:	20170926003	PCN Date:	September 28, 2017
Title:	Datasheet for Datasheet for LMH0397		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMH0397

SNLS558A –APRIL 2017–REVISED SEPTEMBER 2017

Changes from Original (April 2017) to Revision A

Page

• Changed typical power consumption in CD Mode from 315 mW to 290 mW based on updated characterization data	1
• Changed NTps _{max} test condition max from 6 GHz to 50 MHz and < 20 mVp-p NOM to < 10 mVp-p	7
• Changed typical and maximum current dissipation based on updated complete characterization data.....	8
• Changed maximum current dissipation when acquiring lock based on updated complete characterization data	9
• Changed t _{R_F_SDI} minimum SD rise/fall time from 390 ps to 400 ps due to incorrect default settings.....	11
• Changed typical t _R /t _F of OUT0 from 35 ps to 45 ps	11
• Added PRBS10 pattern to clarify AJ _{CD_MODE} and TMJ _{CD_MODE} Test Condition	12
• Changed TMJ _{CD_MODE} maximum spec from 8 UI to 0.45 UI typical because parameter is system dependent	12
• Added SMBUS SCL minimum frequency per SMBus 2.0 specifications	13
• Added Figure 1 to clarify definition of SMBus Timing Parameters in <i>Recommended SMBus Interface Timing Specifications</i>	14
• Added typical characteristic curves for OUT0 VOD and de-emphasis vs. LMH0397 register settings	15
• Added default internal pullup and pulldown settings for 2-level strap pins in Figure 20	30
• Changed clarification in Table 13 regarding reclocker behavior when used with non-SDI data rates	31
• Added Step 6 description in Detailed Design Procedure to include pin and register settings to switch between EQ Mode and CD Mode.	32
• Added mechanical, thermal pad, and land pattern drawings to the <i>Package Option Addendum</i>	41

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMH10397	SNLS558	SNLS558A

The datasheet is considered "custom", for that reason; the document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMH0397RTVR	LMH0397RTVT	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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